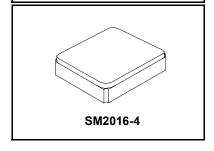


AEC-Q200 This component was always RoHS compliant from the first

date of manufacture.

SF2395H





• Designed for Front End GPS, Beidou, and Glonass Applications

- Steep Rejection
- 2.0 x 1.6 x 1.0 mm Surface-Mount Case
- Complies with Directive 2002/95/EC (RoHS)

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage	3	VDC
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +105	°C
Storage Temperature Range	-40 to +85	°C
Moisture Sensitivity Level	1	MSL
Maximum Soldering Profile	265°C for 10 s	

Electrical Characteristics

Characteristic	Sym	NOTE	-40 to +105°C		UNITS	
Citaracteristic			MIN	TYPICAL	MAX	
Center Frequency	Fc			1224		MHz
Insertion Loss, 1197 to 1249 MHz	IL	3		3.0	3.3	dB
Group Delay Variation 1197 to 1217 MHz				1.4	5	
1217 to 1237 MHz				1.1	5	ns
1242 to 1249 MHz				0.7	5	
Attenuation Referenced to 0 dB:	•	•		•	·	
880 to 920 MHz			22	27		
1710 to 1785 MHz			23	28		40
1850 to 1910 MHz			24	29		- dB
1920 to 1980 MHz			26	31		
2400 to 2500 MHz			30	37		
Temperature Coefficient of Frequency				-80		ppm/°C
Source impedance	Z _S			50		Ω
Load impedance	Z_{L}			50		Ω

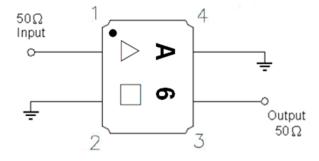
Standard Reel Quantity	Reel Size: 7 inch	2000 Pieces/Reel	
	Reel size: 13 inch	10,000 Pieces/Reel	
ingle-ended Input / Output Impedance Match No matching network required for operation at 50 ohms		No matching network required for operation at 50 ohms	
Package Size		SM2016-4	
Lid Symbolization (Y=year, W=week)		A6, YW	

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. NOTES:

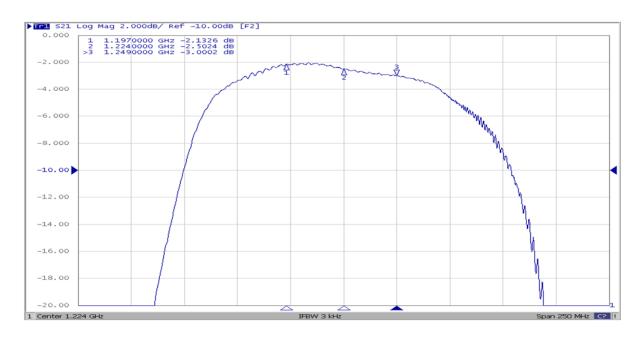
- 1. The design, manufacturing process, and specifications of this device are subject to change.
- 2. US or International patents may apply.
- 3. Maximum insertion loss = 3.0 dB @ 85°C

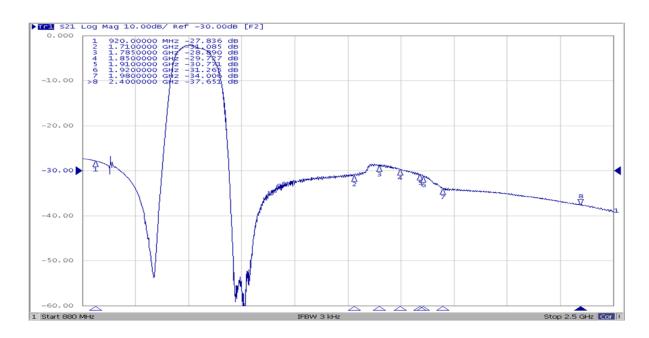
Electrical Connections

Connection Terminals		
Input	1	
Output	3	
Ground	All others	

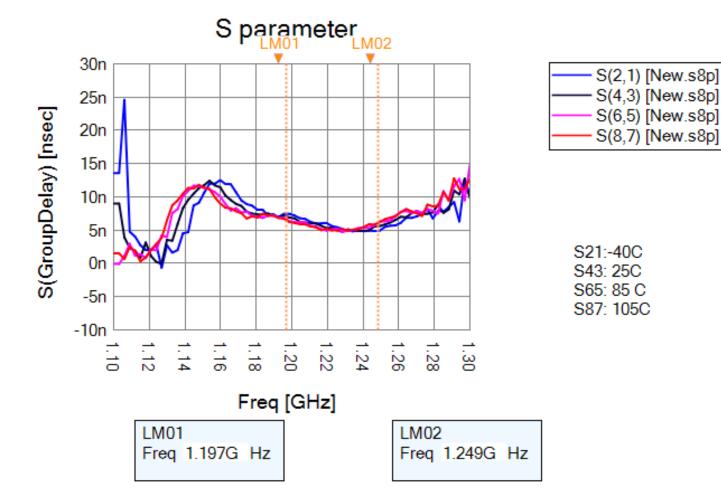


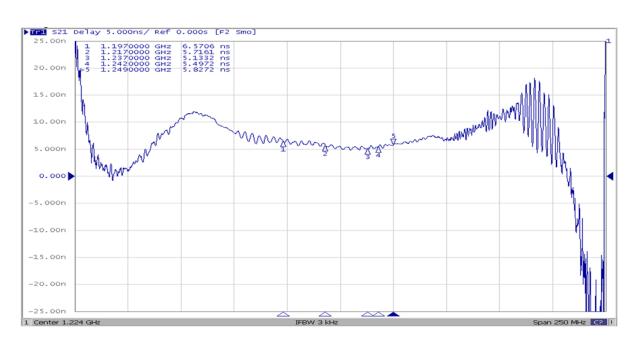
Frequency Characteristics





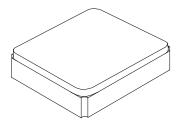
Group Delay





SM2016-4 Case

4-Terminal Ceramic Surface-Mount Case 2.0 X 1.6 mm Nominal Footprint



PCB PAD A U

2.2

1.8

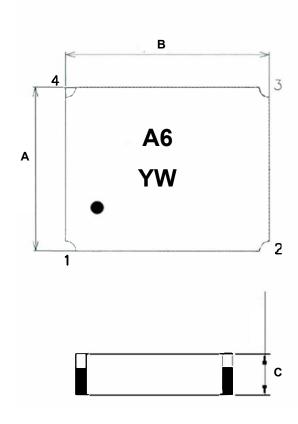
0.6

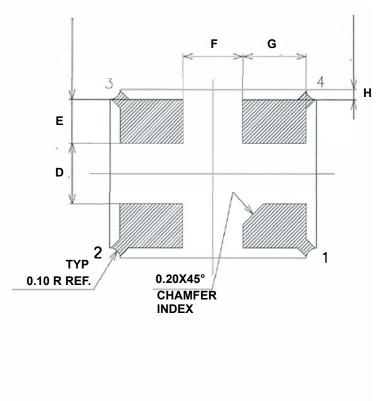
 $\ensuremath{\mathsf{D}}$ mens ons $\ensuremath{\mathsf{n}}$ mm All pads have the same d mens ons

Case Dimensions

Dimension	mm		
	Min	Nom	Max
Α	1.58	1.65	1.72
В	1.98	2.05	2.12
С	0.44	0.52	0.58
D		0.60	
E		0.425	
F		0.425	
G		0.625	
Н		0.10	

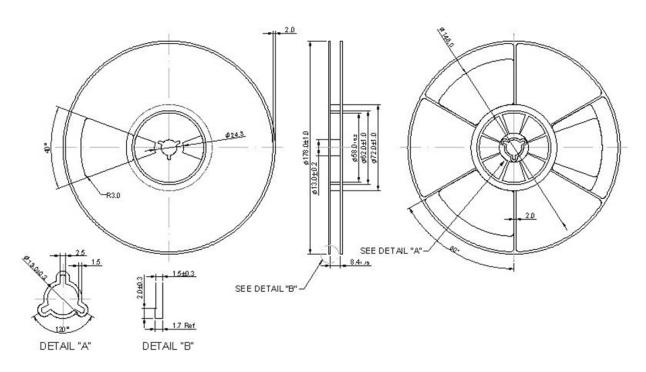
Materials		
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel	
Lid Plating	2.0 to 3.0 µm Nickel	
Body	Al ₂ O ₃ Ceramic	
Pb Free		



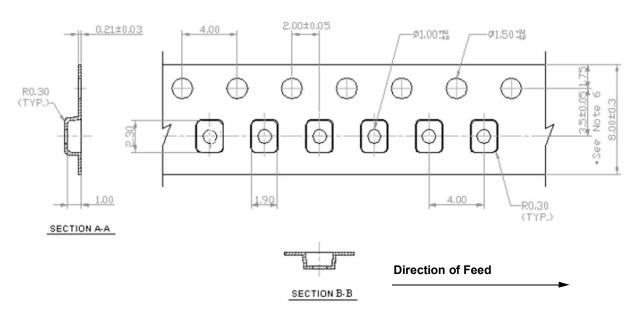


Tape and Reel Standard per ANSI/EIA-481

Reel Dimensions

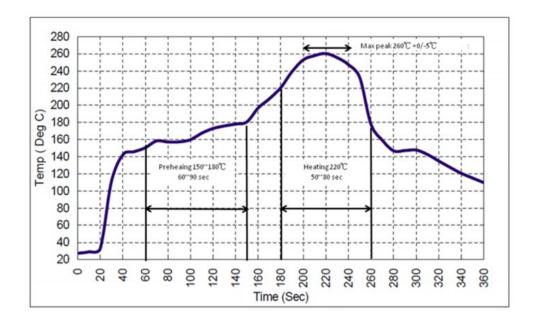


Tape Dimensions



Recommended Reflow Profile

- 1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
- 2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
- 3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
- 4. Time: 5 times maximum.



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RFMi: SF2395H